Appln. S.N. 10/673,762 Amdt. dated February 22, 2006

Reply to Final Office Action of January 26, 2006

Docket No. GP-302388

## In the claims:

(currently amended) A composite structure, comprising:
 a substrate;

at least one metallic layer is partially converted into a carbide layer.

an interfacial barrier laminate formed of at least two layers and disposed over the substrate, wherein the at least two layers include said interfacial barrier laminate comprises at least one ceramic layer disposed adjacent the substrate and at least one metallic layer, and a diamond coating disposed over saidthe interfacial barrier laminate wherein the

- 2. (currently amended) The composite structure according to claim 1 wherein the interfacial barrier laminate contains an interfacial includes at least a third layer selected from the group consisting of high recrystallization temperature amorphous nitrides, high recrystallization temperature amorphous borides, and high recrystallization temperature amorphous carbides, and combinations thereof.
- 3. (currently amended) The composite structure according to claim 2 wherein the interfacial at least a third layer is disposed between said the at least one ceramic layer and said the substrate.
- 4. (currently amended) The composite structure according to claim 1 wherein the interfacial barrier laminate comprises an interfacial layer at least one ceramic layer is selected from the group consisting of borides, nitrides and carbides of transition metals, and combinations thereof.
- 5. (currently amended) The composite structure according to claim 1 wherein the interfacial barrier laminate comprises an interfacial includes at least a third layer selected from the group consisting of TiC, TiCN, TiAl, TiN, CrN, CrC, ZrN, ZrC, WC, SiC, Si<sub>3</sub>N<sub>4</sub> and combinations thereof.

6. (currently amended) The composite structure <u>according to of claim 5</u> wherein the <u>at least a third-interfacial</u> layer is disposed between <del>said the at least one ceramic layer and said the substrate.</del>

- 7. (currently amended) The composite structure according to claim 1 wherein the interfacial barrier laminate contains an interfacial layer of Al<sub>2</sub>O<sub>3</sub> Al<sub>2</sub>O<sub>3</sub> disposed between the at least one ceramic layer and the substrate.
  - 8. (cancelled)
- 9. (currently amended) The composite structure according to claim 1 wherein the <u>at</u>
  <u>least one metallic layer is interfacial barrier laminate contains an interfacial layer-selected from a group consisting of Cr, Ti, Zr, W, Ni, and Si and combinations thereof.</u>
- 10. (original) The composite structure according to claim 1 wherein the interfacial barrier laminate is between 2 μm and 15 μm thick.
- 11. (original) The composite structure according to claim 1 wherein the interfacial barrier laminate is between 5  $\mu m$  and 10  $\mu m$  thick.
- 12. (currently amended) The composite structure according to claim 1 wherein said the at least one ceramic layer of said the interfacial barrier laminate is between 2  $\mu$ m and 5  $\mu$ m thick.
- 13. (currently amended) The composite structure according to claim 1 wherein said the at least one metallic layer of said the interfacial barrier laminate is between 2  $\mu$ m and 7  $\mu$ m thick.

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- 14. (currently amended) The composite structure according to claim 1 wherein said the carbide layer of said the at least one metallic metal layer is between 1 µm and 3 µm thick and faces said the diamond coating.
  - 15. (currently amended) A composite laminate, comprising: a carbon-sensitive substrate;

an interfacial barrier laminate configured to inhibit the diffusion of carbon, said the interfacial barrier laminate formed of at least two layers including comprising a metallic layer and a ceramic layer, said the ceramic layer being disposed adjacent said the carbon-sensitive substrate; and

a carbide-rich coating disposed over said-the interfacial barrier laminate; and a diamond layer disposed over the carbide-rich coating.

- 16. (currently amended) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises an interfacial includes at least a third layer selected from the group consisting of high recrystallization temperature amorphous nitrides, high recrystallization temperature amorphous borides, and high recrystallization temperature amorphous carbides, and combinations thereof disposed between said ceramic and said substrate.
- 17. (currently amended) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises an interfacial layer ceramic layer is selected from the group consisting of borides, nitrides and carbides of transition metals, and combinations thereof.
- 18. (currently amended) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises an interfacial includes at least a third layer disposed between the said-substrate and the carbide-rich coating, wherein the at least a third layer is said carbide layer-selected from the group consisting of TiC, TiCN, TiAl, TiN, CrN, CrC, ZrN, ZrC, and combinations thereof.

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19. (currently amended) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises an interfacial layer of Al<sub>2</sub>O<sub>3</sub> Al<sub>2</sub>O<sub>3</sub> disposed between said the substrate and said the carbide-rich coating layer.

- 20. (currently amended) The composite laminate according to claim 15 wherein the metallic layer is interfacial barrier laminate comprises an interfacial layer selected from the group consisting of Cr, Ti, Zr, Si, W, Ni, and combinations thereof, and wherein the metallic layer is disposed between said the ceramic layer substrate and said the carbide-rich coating layer.
- 21. (currently amended) The composite laminate according to claim 15 wherein the metallic layer of the interfacial barrier laminate is a metal which forms carbides in the presence of carbon.
- 22. (currently amended) The composite laminate according to claim 15 wherein the interfacial barrier laminate is between 5 μm and 10 μm thick.
  - 23. (cancelled)
  - 24. (cancelled)
- 25. (original) The composite laminate according to claim 15 wherein the substrate comprises steel.
- 26. (currently amended) The composite laminate according to claim 15 wherein the substrate comprises cemented carbide.
  - (withdrawn) A cutting tool comprising:
     a carbon sensitive substrate;

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a ceramic layer disposed over the carbon sensitive substrate configured to inhibit the diffusion of carbon;

- a metallic layer disposed over the ceramic layer;
- a carbide layer disposed over said metallic layer; and
- a diamond layer disposed over said carbide layer.
- (withdrawn) The cutting tool according to claim 27 wherein the carbon sensitive 28. substrate is steel.
- (withdrawn) The cutting tool according to claim 28 wherein steel is heat-treated 29. after the diamond deposition, resulting in a substrate with a martensite structure.
- (withdrawn) The cutting tool according to claim 27 wherein the carbon sensitive 30. substrate is cemented carbide.
- (withdrawn) The cutting tool according to claim 27 comprising an interfacial 31. layer disposed between said substrate and said diamond layer selected from the group consisting of borides, nitrides and carbides of transition materials and combinations thereof.
- (withdrawn) The cutting tool according to claim 27 comprising an interfacial 32. layer selected from the group consisting of TiC, TiCN, TiAl, TiN, CrN, CrC, ZrN, ZrC and combinations thereof disposed between said substrate and said diamond layer.
- (withdrawn) The cutting tool insert according to claim 27 comprising an 33. interfacial layer of Al<sub>2</sub>0<sub>3</sub> disposed between said substrate and said diamond layer.
- (withdrawn) The cutting tool according to claim 27 comprising an interfacial 34. layer selected from the group consisting of Cr, Ti, Zr, and Si and combinations thereof disposed between said substrate and said diamond layer.

35. (withdrawn) The cutting tool according to claim 27 further comprising a layer of mixed sp2- and sp3-bonded carbon.

- 36. (withdrawn) A method of forming a composite structure comprising the steps of:

  providing carbon sensitive substrate;

  disposing a layer of ceramic on the substrate;

  disposing a layer of metal on the ceramic;

  disposing a layer of material containing carbon on the metal under conditions sufficient to convert a portion of the layer of metal into carbide.
- 37. (withdrawn) The method according to claim 36 wherein providing a carbon sensitive substrate is providing one of steel or cemented carbide.
- 38. (withdrawn) The method according to claim 36 further comprising the step of heat treating the composite structure.
- 39. (withdrawn) The method according to claim 36 wherein disposing a layer of metal is disposing a layer of metal between 2 μm and 7 μm thick.
- 40. (withdrawn) The method according to claim 36 wherein disposing a layer of carbon is disposing a layer of material containing carbon such that between 1 μm and 3 μm of metal is converted into carbide.
- 41. (withdrawn) The method according to claim 36 wherein disposing a layer of carbon is disposing a layer of diamond.
- 42. (new) The composite structure according to claim 1 wherein the interfacial barrier laminate comprises at least two ceramic layers.

- 43. (new) The composite structure according to claim 1 wherein the interfacial barrier laminate comprises at least two metallic layers.
- 44. (new) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises at least two ceramic layers.
- 45. (new) The composite laminate according to claim 15 wherein the interfacial barrier laminate comprises at least two metallic layers.